

# HEF4040B

## 12-stage binary ripple counter

Rev. 9 — 23 March 2016

Product data sheet

### 1. General description

The HEF4040B is a 12-stage binary ripple counter with a clock input ( $\overline{CP}$ ), an overriding asynchronous master reset input (MR) and twelve fully buffered outputs (Q0 to Q11). The counter advances on the HIGH-to-LOW transition of  $\overline{CP}$ . A HIGH on MR clears all counter stages and forces all outputs LOW, independent of  $\overline{CP}$ . Each counter stage is a static toggle flip-flop. The clock input is highly tolerant of slow rise and fall times due to its Schmitt trigger action.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

### 2. Features and benefits

- Tolerant of slow clock rise and fall time
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

### 3. Applications

- Frequency dividing circuits
- Time delay circuits
- Control counters

### 4. Ordering information

Table 1. Ordering information

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ .

Type number	Package		Version
	Name	Description	
HEF4040BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



### 5. Functional diagram

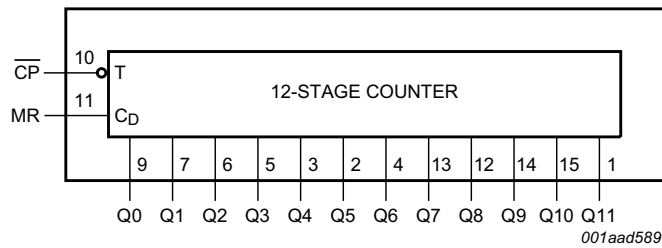


Fig 1. Functional diagram

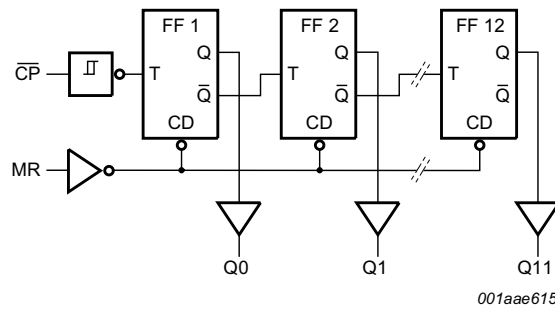


Fig 2. Logic diagram

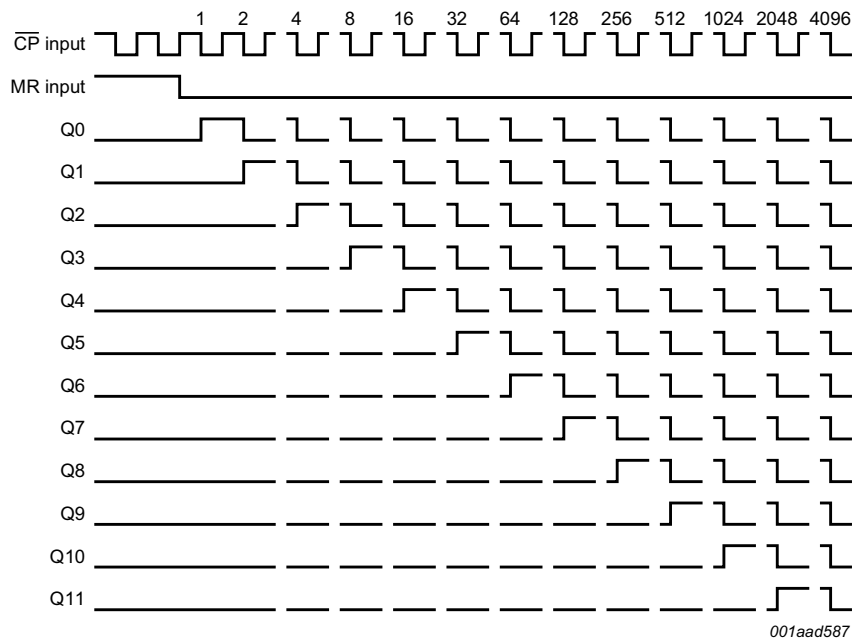
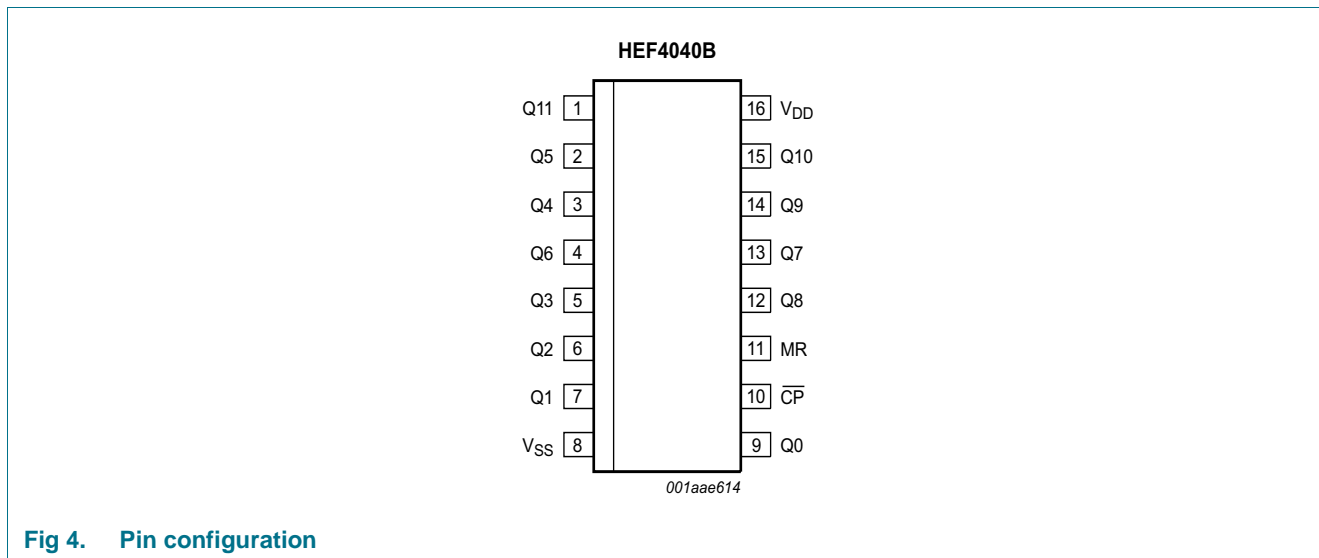


Fig 3. Timing diagram

## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V <sub>SS</sub>	8	ground supply voltage
Q0 to Q11	9, 7, 6, 5, 3, 2, 4, 13, 12, 14, 15, 1	parallel output
$\overline{CP}$	10	clock input (HIGH-to-LOW edge-triggered)
MR	11	master reset input (active HIGH)
V <sub>DD</sub>	16	supply voltage

## 7. Limiting values

**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{DD} + 0.5\text{ V}$	-	$\pm 10$	mA
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{DD} + 0.5\text{ V}$	-	$\pm 10$	mA
$I_{I/O}$	input/output current		-	$\pm 10$	mA
$I_{DD}$	supply current		-	50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		-40	+85	°C
$P_{tot}$	total power dissipation	SO16 package [1]	-	500	mW
$P$	power dissipation	per output	-	100	mW

[1] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

## 8. Recommended operating conditions

**Table 4. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	supply voltage		3	-	15	V
$V_I$	input voltage		0	-	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5\text{ V}$	-	-	3.75	ms/V
		$V_{DD} = 10\text{ V}$	-	-	0.5	ms/V
		$V_{DD} = 15\text{ V}$	-	-	0.08	ms/V

## 9. Static characteristics

**Table 5. Static characteristics**

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ °C}$		$T_{amb} = 25\text{ °C}$		$T_{amb} = 85\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V

**Table 5. Static characteristics ...continued**  
 $V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = 25\text{ }^{\circ}\text{C}$		$T_{amb} = 85\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	mA
			5 V	-	-0.52	-	-0.44	-	-0.36	mA
			10 V	-	-1.3	-	-1.1	-	-0.9	mA
			15 V	-	-3.6	-	-3.0	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.52	-	0.44	-	0.36	-	mA
			10 V	1.3	-	1.1	-	0.9	-	mA
			15 V	3.6	-	3.0	-	2.4	-	mA
$I_{LI}$	input leakage current		15 V	-	$\pm 0.3$	-	$\pm 0.3$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	$I_O = 0\text{ A}$	5 V	-	20	-	20	-	150	$\mu\text{A}$
			10 V	-	40	-	40	-	300	$\mu\text{A}$
			15 V	-	80	-	80	-	600	$\mu\text{A}$
$C_I$	input capacitance		-	-	-	-	7.5	-	-	pF

## 10. Dynamic characteristics

**Table 6. Dynamic characteristics**  
 $V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; unless otherwise specified; for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula <sup>[1]</sup>	Min	Typ	Max	Unit		
$t_{PHL}$	HIGH to LOW propagation delay	$\overline{CP} \rightarrow Q_0$ see <a href="#">Figure 5</a>	5 V	$78\text{ ns} + (0.55\text{ ns/pF})C_L$	-	105	210	ns		
			10 V	$34\text{ ns} + (0.23\text{ ns/pF})C_L$	-	45	90	ns		
			15 V	$27\text{ ns} + (0.16\text{ ns/pF})C_L$	-	35	70	ns		
		$Q_n \rightarrow Q_{n+1}$	5 V	<sup>[2]</sup> $(0.55\text{ ns/pF})C_L$	-	35	70	ns		
			10 V	<sup>[2]</sup> $(0.23\text{ ns/pF})C_L$	-	15	30	ns		
			15 V	<sup>[2]</sup> $(0.16\text{ ns/pF})C_L$	-	10	20	ns		
		$MR \rightarrow Q_n$ see <a href="#">Figure 5</a>	5 V	$63\text{ ns} + (0.55\text{ ns/pF})C_L$	-	90	180	ns		
			10 V	$29\text{ ns} + (0.23\text{ ns/pF})C_L$	-	40	80	ns		
			15 V	$22\text{ ns} + (0.16\text{ ns/pF})C_L$	-	30	60	ns		
$t_{PLH}$	LOW to HIGH propagation delay	$\overline{CP} \rightarrow Q_0$ see <a href="#">Figure 5</a>	5 V	$58\text{ ns} + (0.55\text{ ns/pF})C_L$	-	85	170	ns		
			10 V	$29\text{ ns} + (0.23\text{ ns/pF})C_L$	-	40	80	ns		
			15 V	$22\text{ ns} + (0.16\text{ ns/pF})C_L$	-	30	60	ns		
		$Q_n \rightarrow Q_{n+1}$	5 V	<sup>[2]</sup> $(0.55\text{ ns/pF})C_L$	-	35	70	ns		
			10 V	<sup>[2]</sup> $(0.23\text{ ns/pF})C_L$	-	15	30	ns		
			15 V	<sup>[2]</sup> $(0.16\text{ ns/pF})C_L$	-	10	20	ns		
		$t_t$	transition time	see <a href="#">Figure 5</a>	5 V	<sup>[3]</sup> $10\text{ ns} + (1.00\text{ ns/pF})C_L$	-	60	120	ns
					10 V	$9\text{ ns} + (0.42\text{ ns/pF})C_L$	-	30	60	ns
					15 V	$6\text{ ns} + (0.28\text{ ns/pF})C_L$	-	20	40	ns

**Table 6. Dynamic characteristics ...continued**

$V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ °C}$ ; unless otherwise specified; for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	V <sub>DD</sub>	Extrapolation formula <sup>[1]</sup>	Min	Typ	Max	Unit
t <sub>w</sub>	pulse width	$\overline{\text{CP}}$ input HIGH; minimum width; see <a href="#">Figure 5</a>	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		MR input HIGH; minimum width; see <a href="#">Figure 5</a>	5 V		40	20	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
t <sub>rec</sub>	recovery time	MR input; see <a href="#">Figure 5</a>	5 V		40	20	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
f <sub>max</sub>	maximum frequency	$\overline{\text{CP}}$ input; see <a href="#">Figure 5</a>	5 V		10	20	-	MHz
			10 V		15	30	-	MHz
			15 V		25	50	-	MHz

- [1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C<sub>L</sub> in pF).
- [2] For loads other than 50 pF at the n<sup>th</sup> output, use the slope given.
- [3] t<sub>i</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

**Table 7. Dynamic power dissipation P<sub>D</sub>**

P<sub>D</sub> can be calculated from the formulas shown.  $V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ °C}$ .

Symbol	Parameter	V <sub>DD</sub>	Typical formula for P <sub>D</sub> (μW)	where:
P <sub>D</sub>	dynamic power dissipation	5 V	$P_D = 400 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f <sub>i</sub> = input frequency in MHz, f <sub>o</sub> = output frequency in MHz, C <sub>L</sub> = output load capacitance in pF, V <sub>DD</sub> = supply voltage in V, Σ(f <sub>o</sub> × C <sub>L</sub> ) = sum of the outputs.
		10 V	$P_D = 2000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	
		15 V	$P_D = 5200 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	

11. Waveforms

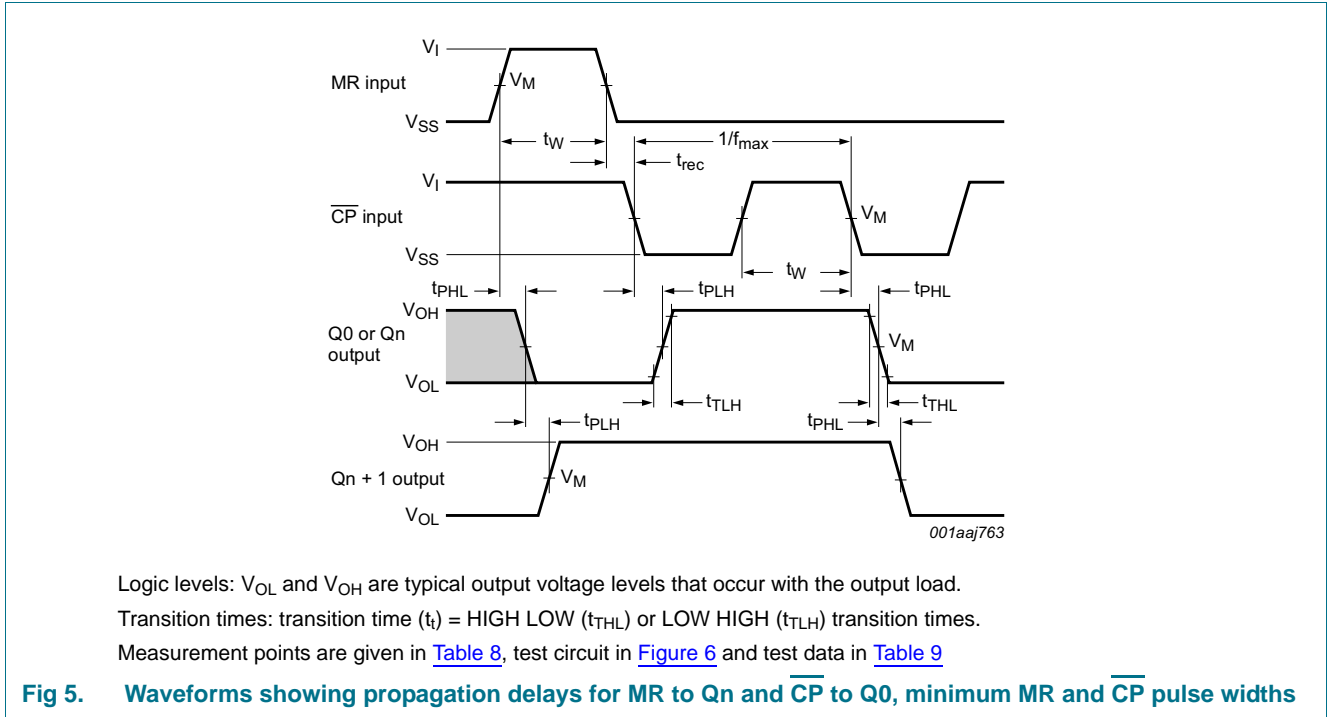
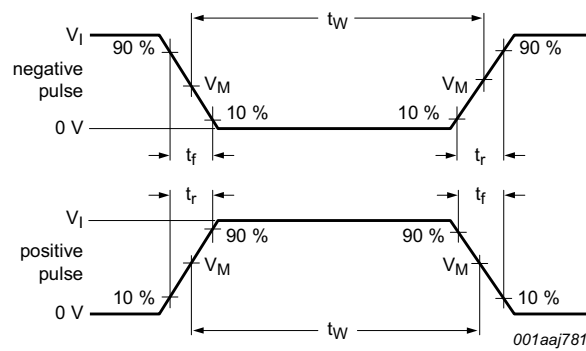
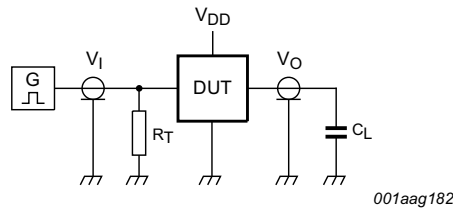


Table 8. Measurement points

Supply voltage	Input		Output
$V_{DD}$	$V_I$	$V_M$	$V_M$
5 V to 15 V	$V_{DD}$ or $V_{SS}$	$0.5V_{DD}$	$0.5V_{DD}$



a. Input waveforms



b. Test circuit

Test data is given in [Table 9](#).

Definitions test circuit:

DUT = Device Under Test;

$C_L$  = load capacitance, including the jig and probe capacitance;

$R_L$  = load resistance, which should be equal to the output impedance of the pulse generator.

**Fig 6. Test circuit for measuring switching times**

**Table 9. Test data**

Supply voltage	Input		Load
$V_{DD}$	$V_I$	$t_r, t_f$	$C_L$
5 V to 15 V	$V_{SS}$ or $V_{DD}$	$\leq 20$ ns	50 pF



12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

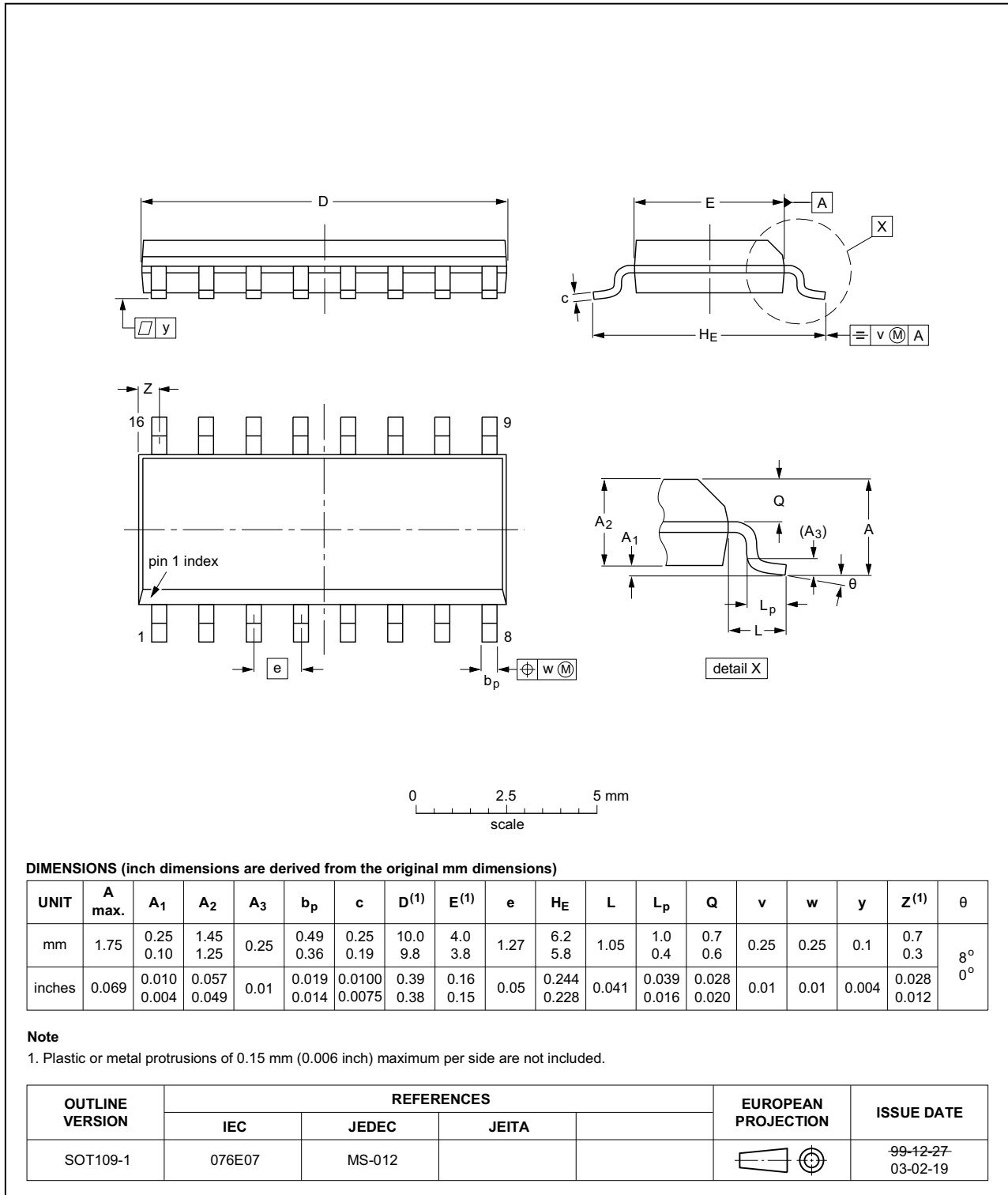


Fig 7. Package outline SOT109-1 (SO16)

## 13. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4040B v.9	20160323	Product data sheet	-	HEF4040B v.8
Modifications:	<ul style="list-style-type: none"> <li>Type number HEF4040BP (SOT38-4) removed.</li> </ul>			
HEF4040B v.8	20111117	Product data sheet	-	HEF4040B v.7
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> <li>Changes in "General description" and "Features and benefits".</li> </ul>			
HEF4040B v.7	20111010	Product data sheet	-	HEF4040B v.6
HEF4040B v.6	20091125	Product data sheet	-	HEF4040B v.5
HEF4040B v.5	20090709	Product data sheet	-	HEF4040B v.4
HEF4040B v.4	20090304	Product data sheet	-	HEF4040B_CNV v.3
HEF4040B_CNV v.3	19950101	Product specification	-	HEF4040B_CNV v.2
HEF4040B_CNV v.2	19950101	Product specification	-	-

## 14. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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